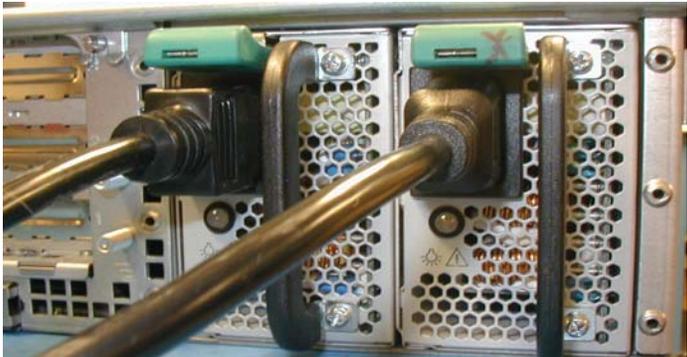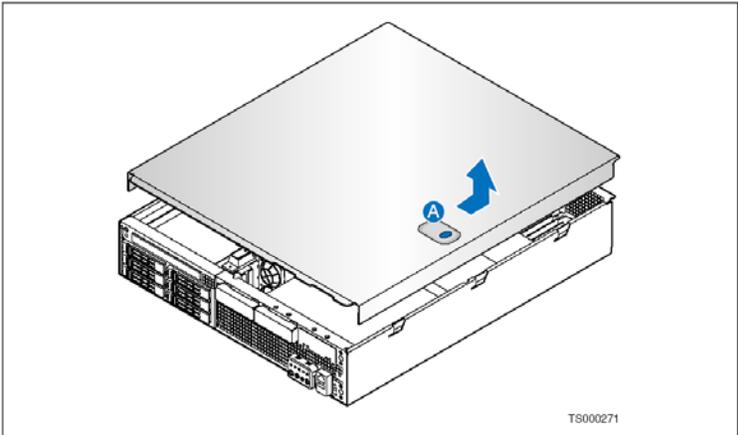| NEI	**Work Instruction**	Page 1 of 20
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Assemblies Covered: **C-2500 (786-0067-XX)**		

Revision	Date	ECO #	Revised By	Description of Changes
0A			Tim Connolly	Original Release

Tools Required:

- #2 Phillips Screwdriver
- #1 Phillips Screwdriver

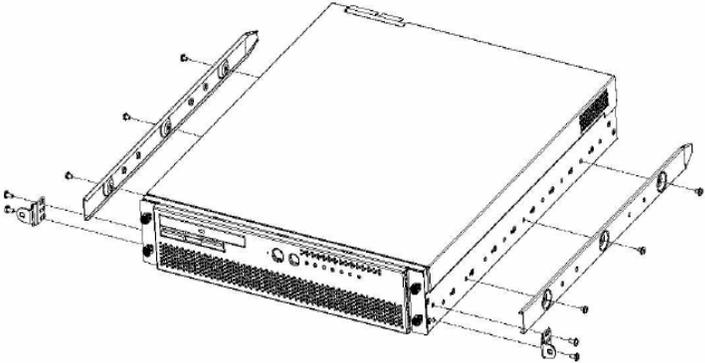| NEI	**Work Instruction**	Page 2 of 20
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1.	Removal of the power cord does not require any tools a. Remove the power cord(s) first.	

2.	Removal of the top access cover needs a # 2 screwdriver.
	    a. Remove the shipping screw, if present.
	    b. While holding the blue button at the top of the chassis in ("A"), slide the top cover back until it stops.
	    c. Lift the cover straight up to remove it from the server.
	    d. Discard sheet metal cover and screw in appropriate recycle bin.	

3.	Removal of the rails (if present) requires a #2 Phillips screwdriver.
	    a. Remove rack mount ears
	    b. Remove slide rails on both sides
	    c. Discard the metal rails, rack ears and screws in the appropriate recycle bin.	

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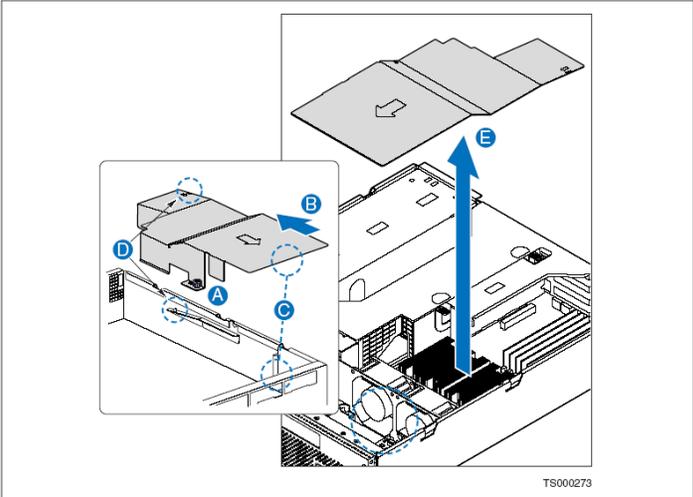| Document Number / Disk File: 597-786-0067-00	By: Tim Connolly	Current Rev: 0A	Date: 1/15/09

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4.	Removal of the Front bezel requires a #2 Philips screwdriver.
	   a. Disconnect the cables from the front panel 4xGbE connectors if they are installed.
	   b. Remove the bezel retention screw (right side, if present). ("A")
	   c. Rotate the bezel outward as shown and remove. ("B")
	   d. Discard the Rack Ears and screws in the appropriate recycle bin.
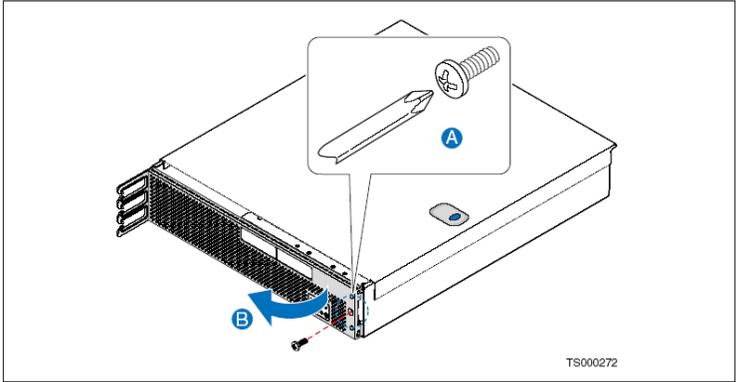		
		TS000272

5.	Removal of the power supply module(s) does not require any tools.
	   a. Press and hold the green safety lock downward to disengage the power supply module.
	   b. Grasp the handle ("B") and pull the power supply module from the chassis.
	   c. Discard the Power Supply Module(s) in the appropriate recycle bin.
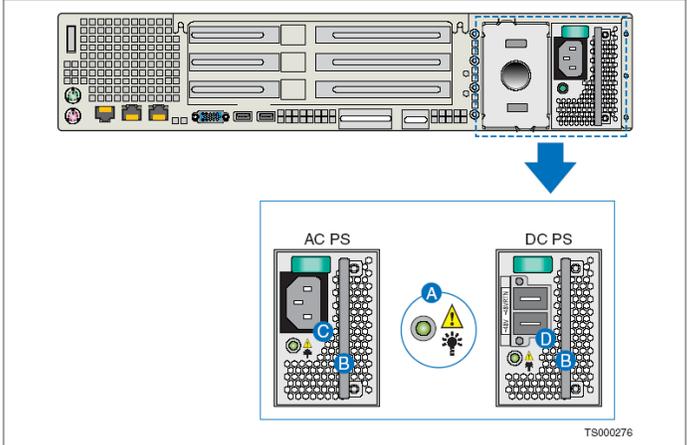		
		AC PS DC PS
		TS000276

6.	Removal of the Processor Air Duct requires a #2 Philips screwdriver.
	
	   a. Using #2 Philips screwdriver loosen the captive fastener on the air duct. ("A")
	   b. Slide the duct several millimeters toward the rear panel until it stops. ("B") The front edge will disengage from the front panel. ("C") The metal tab at the rear will release. ("D")
	   c. Lift the air duct straight up and remove it from the chassis. ("E")
	   d. Discard the Processor Air Duct in the appropriate recycle bin.
		
		TS000273

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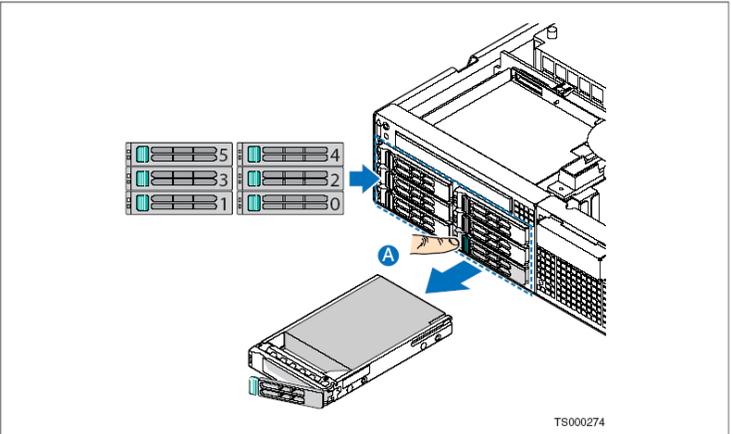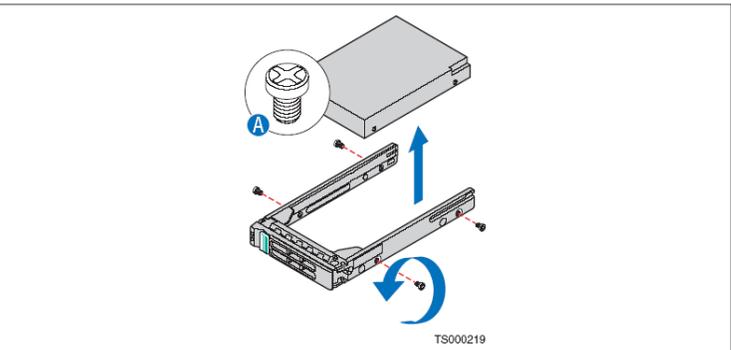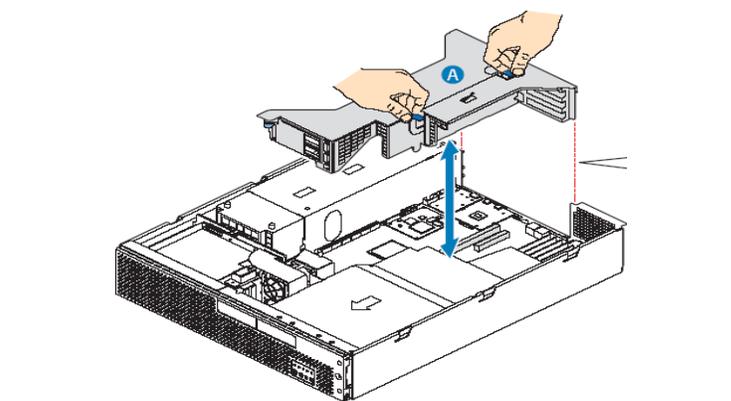| Document Number / Disk File: 597-786-0067-00	By: Tim Connolly	Current Rev: 0A	Date: 1/15/09

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7.	Removal of the Hard Drive(s) requires a #1 Philips screwdriver.
	
	  a. Remove the drive tray(s) by pressing the green button to open the lever. ("A")
	  b. Pull the drive assembly out of the chassis.
		TS000274

7.	c. Use a #1 Screwdriver to remove the four screws that attach it to the drive tray. ("A") **d. Discard the hard drive(s), drive bracket(s), and screws in the appropriate recycle bin.**	TS000219
8.	Removal of the PCI addon cards, riser, and rear card cage bracket requires a #2 Philips screwdriver. a. Grasp the PCI riser card assembly using the two flexible blue handles and carefully pull the assembly out of the chassis. ("A")	

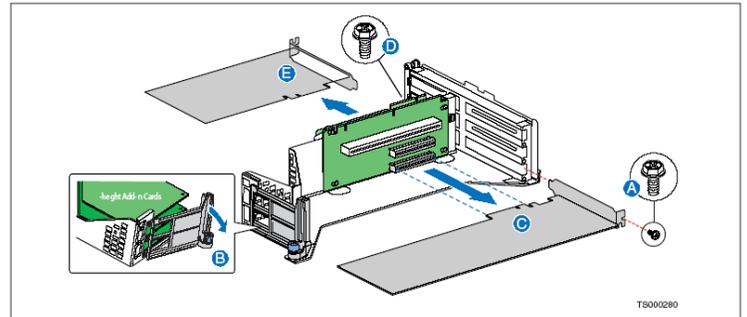| NEI	Work Instruction	Page 5 of 20
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8.

   b. One at a time, remove screws for any PCI cards or filler plates, and then pull away from the riser to remove.

   c. When removing a full-height add-in card, remove the front retention clip by loosening the blue captive screw and rotating the clip outward. ("B") Disengage the three plastic tabs from the metal sidewall.

   d. Remove the two (2) screws securing the full-height riser to the card cage base, slide the riser several millimeters toward the rear panel and pull it off.

   e. Remove the two (2) screws securing the low-profile riser to the card cage base and slide the riser several millimeters toward the rear panel and pull it off.

   f. If present remove the six (6) EMI clips from the rear card cage bracket.

   g. **Discard the add-in card(s) riser, filler plate(s), card cage base, rear card cage bracket, EMI clips, and screws in the appropriate recycle bin**

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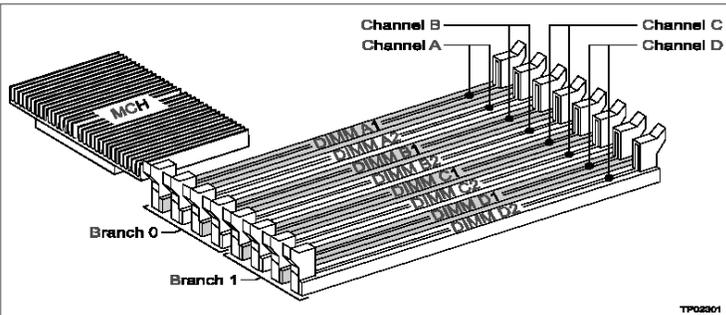| Document Number / Disk File: 597-786-0067-00	By: Tim Connolly	Current Rev: 0A	Date: 1/15/09

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| 9.	Removal of the Heat Sink requires a #2 Phillips screwdriver. a. Loosen the four captive screws on the corners of the heat sink with a #2 Phillips screwdriver. ("A") b. Twist the heat sink slightly to break the seal between the heat sink and the processor. ("B") c. Lift the heat sink from the processor. If it does not pull up easily, twist the heat sink again. **d. Discard the Heat Sink in the appropriate recycling bin.**	
10.	Removal of the CPU does not require any tools. b. Lift the CPU latch out and up to unfasten the CPU. c. Carefully pick up the CPU on both sides and lift it off the board. **d. Discard the CPU in the appropriate Recycle Bin.**	
11.	Removal of the memory DIMMs and Battery from the motherboard. a. Remove each of the memory DIMMs by pushing down and out on the two latches, one on each end of the DIMM connector. Lift memory DIMM straight out to remove. b. Remove the coin style Lithium Battery. **c. Discard the memory DIMMs in the appropriate recycle bin.** **d. Discard the Lithium Battery in the appropriate recycle bin.** ***** CAUTION *****	
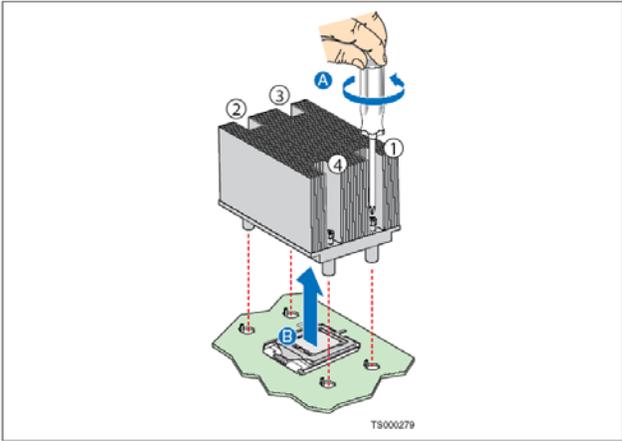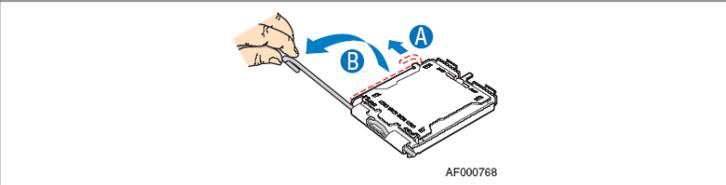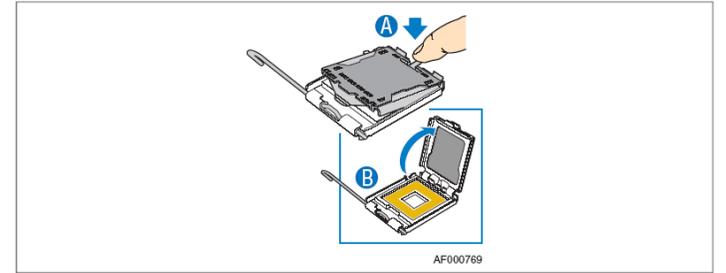
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|		
	Care should be observed when disposing of the battery to avoid shorting it!	
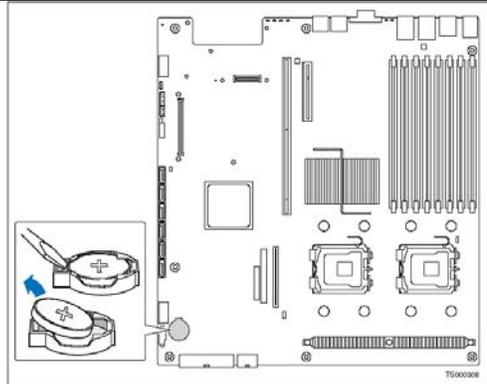
12.	Removal of the CPU fan Assembly requires a #2 Phillips screwdriver.
	
	  a. Unplug the CPU fan assembly power cables from the front panel board. ("A")
	  b. Loosen the blue thumbscrew fastener on the CPU fan assembly bracket. ("B") with a #2 Phillips screwdriver.
	  c. Lift the fan assembly out of the chassis.	
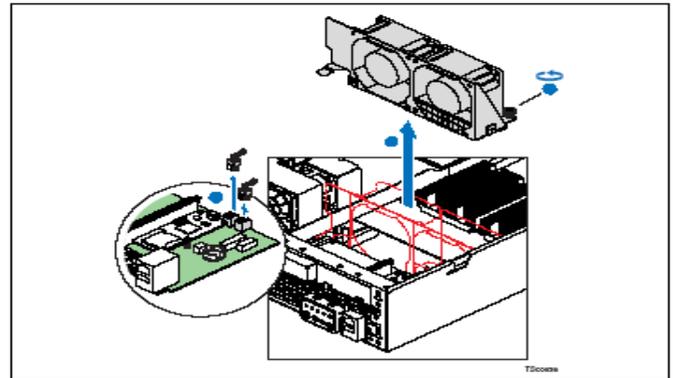
12.	Removal of the Fans from the CPU Fan Assembly does not require any tools.
	
	  d. Remove the rivets connecting the fans to the bracket. ("A")
	  e. Loosen the blue thumbscrew fastener on the CPU fan assembly bracket ("B").
	  f. Lift the fan assembly out of the chassis.
	  g. Discard the Fans, CPU Fan Assembly, and rivets in the appropriate recycle bin.	
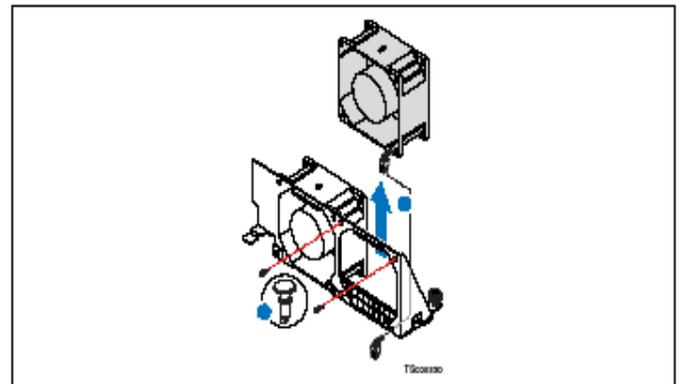
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13.	Removal of the PCI Fan Assembly requires a #2 Philips screwdriver. a. Remove the flex cable support bracket from the chassis. ("A") b. Disconnect the flex cable from the SAS backplane board and lift the cable off of the PCI fan assembly.	
13.	c. Disconnect the PCI fan assembly power cables from the SAS front panel (SFP) board. ("A") d. Remove the PCI fan bracket by loosening the screw that fastens it to the drive bay subassembly using a #2 Philips screwdriver. ("B") e. Lift the fan assembly out of the chassis	

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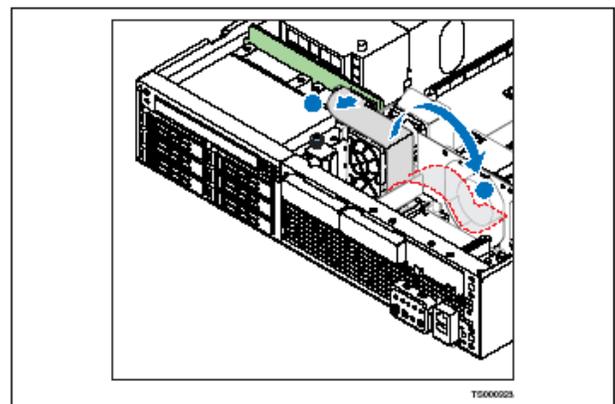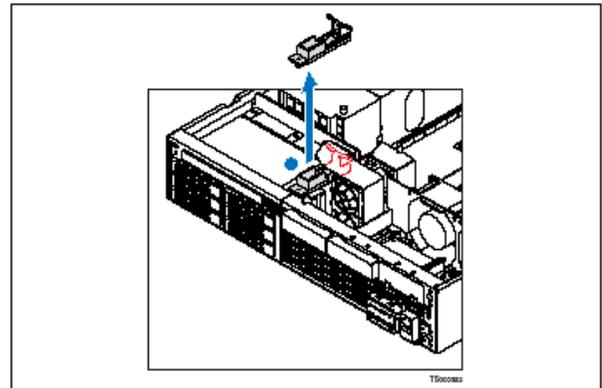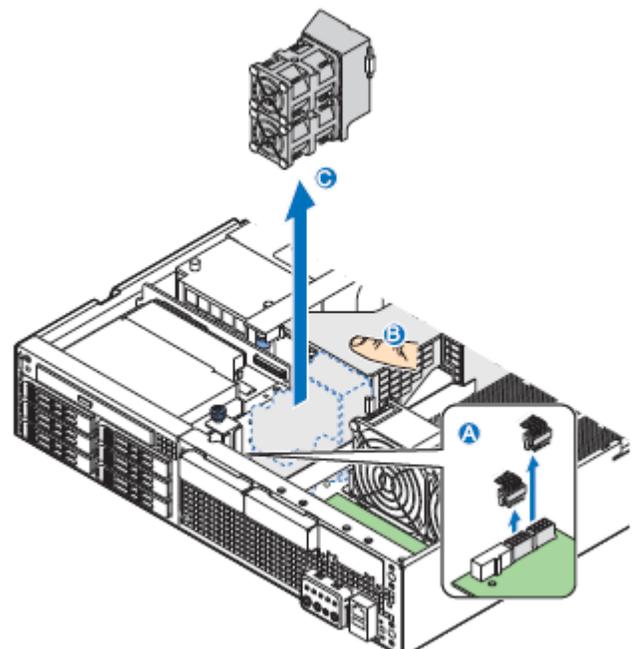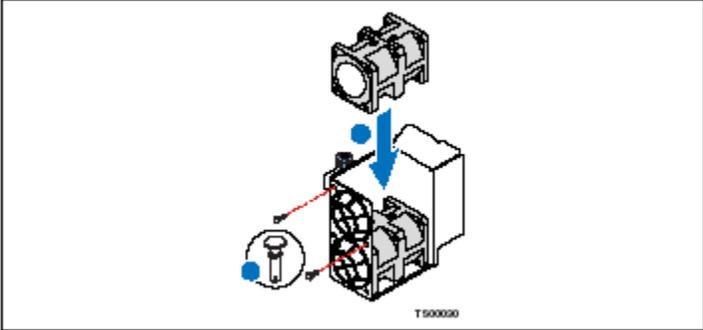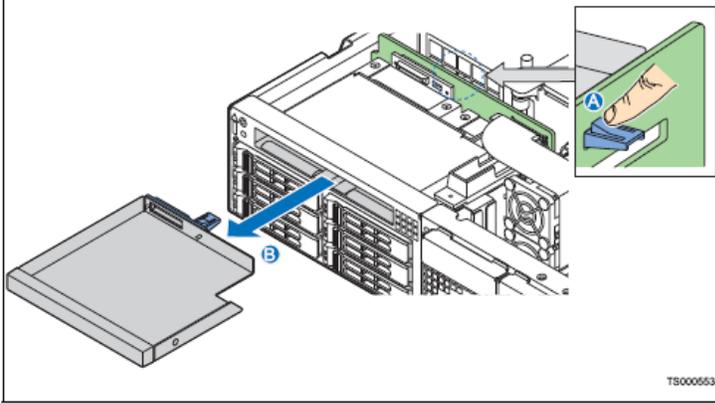| Document Number / Disk File: 597-786-0067-00 | By: Tim Connolly | Current Rev: 0A | Date: 1/15/09 |
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14.	Removal of the Fans from the PCI Fan Assembly requires no tools. a. Remove two push rivets for each fan, and lift the fans out of the assembly. **b. Discard the Fans, PCI Fan Assembly, and rivets in the appropriate recycle bin.**	
15.	Removal of optical assembly (if present) requires a #1 Philips screwdriver. a. Press on the blue latch ("A") on the back of the SAS backplane to release the optical assembly from the backplane. b. Remove the filler panel from the chassis.	
16.	c. Remove the two (2) screws securing the blue tab to the rear of the drive using #1 Philips screwdriver.. **d. Discard the Optical Drive, Plastic guide, and screws in the appropriate Recycling Bin.**	

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17.	Removal of the Bridge Board does not require any tools. a. Open the retention clips of the Bridge Board on the mid-plane, and motherboard. b. Pull the Bridge Board straight up to remove. **c. Discard the Bridge Board in the appropriate Recycling Bin.**	
18.	Removal of the IO Expansion Module, if present, does not require any tools. a. Lift the IO Expansion module straight up until it disengages from the standoffs and connector on the motherboard. **b. Discard the IO Expansion Module in the appropriate recycling bin.**	
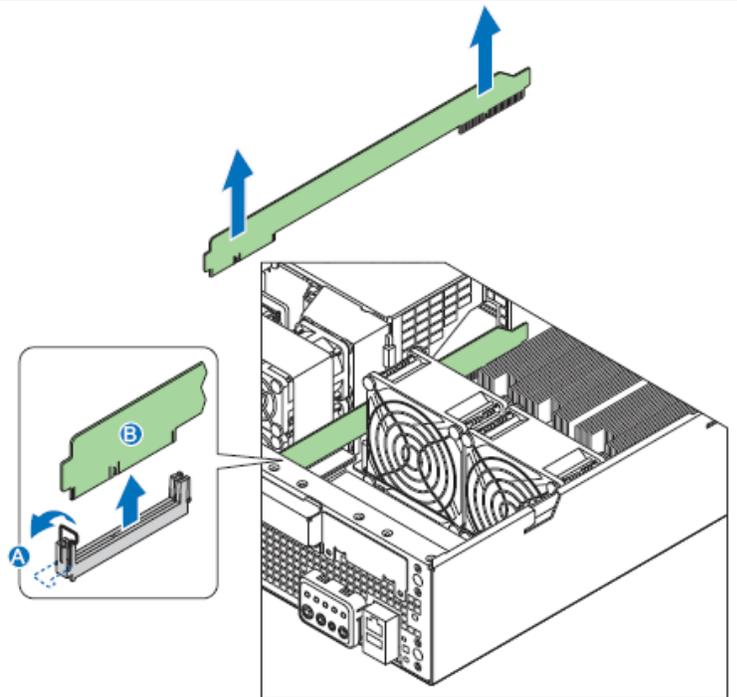
Unit Disassembly for WEEE

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19.	Removal of the RMM and/or GCM3 Module does not require any tools.
	   a. Pull the module(s) straight up from the motherboard, until it disengages the standoffs and connector.
	   b. Discard the RMM and/or GCM3 Module in the appropriate recycling bin.	
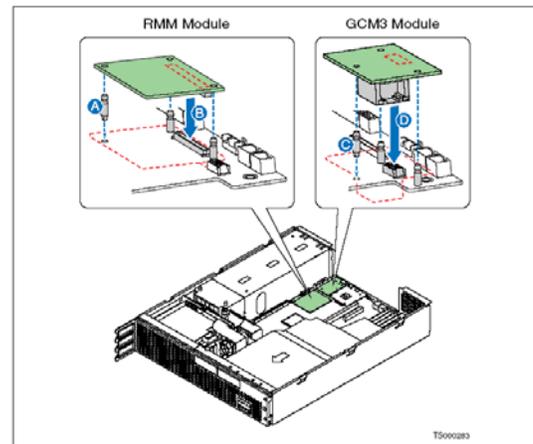
20.	Removal of the Intel Value Solid State Drive (VSSD), if present, requires a #? Screwdriver.
	   a. Remove the screw holding the VSSD to the Interposer board ("E").
	   b. Lift the VSSD off the Interposer board.	

20.	c. Detach the cable connecting the Interposer board to the motherboard.
	   d. Remove the two screws securing the Interposer board. ("B")
	   e. Lift the Interposer board straight off the motherboard to complete the removal.
	   f. Discard the Intel VSSD, Interposer Board, cable, and screws in the appropriate recycling bin.	

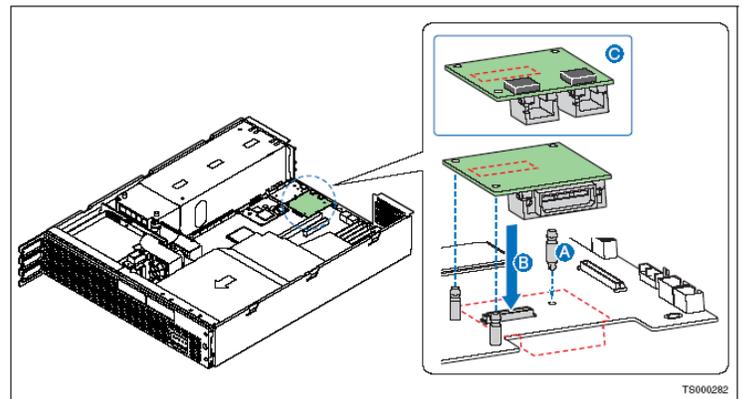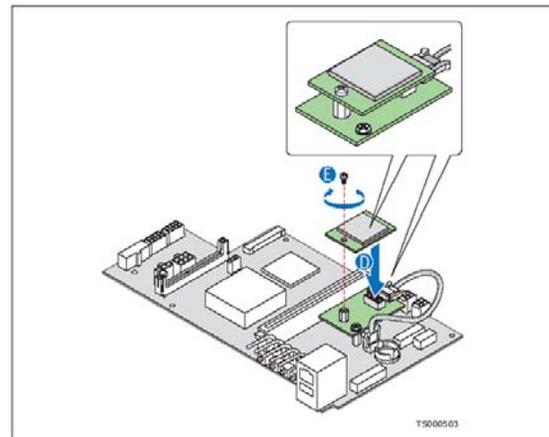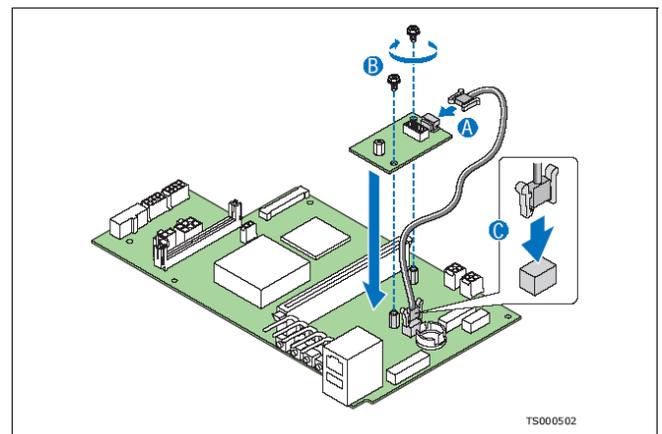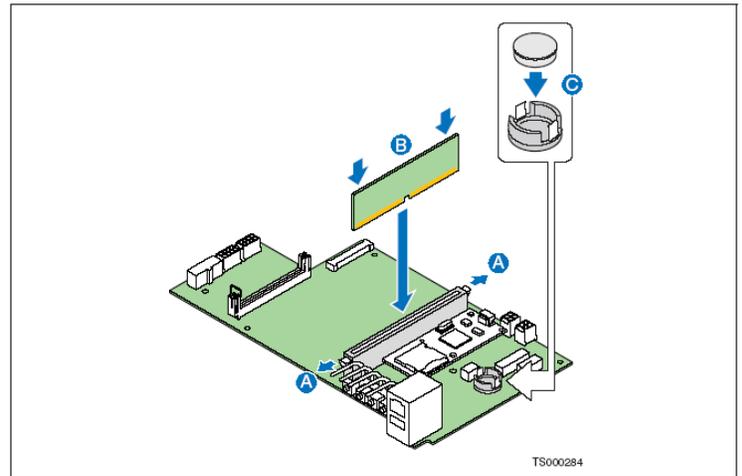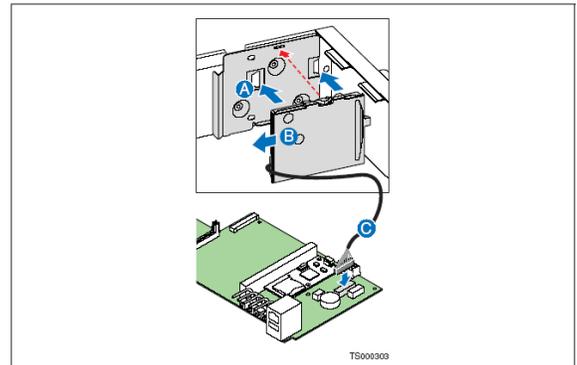| NEI	Work Instruction	
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21.	Removal of the RAID DIMM and RAID Key (if installed) does not require any tools. a. Press down on the two latches on either side of the RAID DIMM. ("B") b. Lift the RAID DIMM out of the connector. ("A") c. Remove the RAID Key from it's socket. ("C") **d. Discard the RAID DIMM and the RAID Key in the appropriate recycling bin.**	 TS000284

22.	Removal of the RAID Intelligent Battery Backup Unit (IBBU) requires a #2 Phillips screwdriver.
	   a. Disconnect the cable from the IBBU to the connector on the SFP board. ("C")
	   b. Slide the IBBU toward the front panel to unlock it. ("B") Remove from the chassis.
		
		TS000303

22.	c. Open the battery assembly case, and disconnect the battery cable. ("B") d. Unplug the battery power cable from the battery assembly case, and remove the battery pack. ("B") ** e. Discard the battery pack, the battery cable, and the battery assembly case in the appropriate recycling bin.**	 TS000302 TS000301

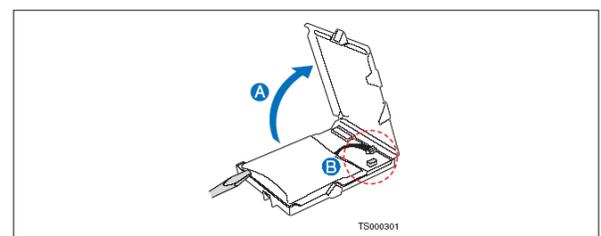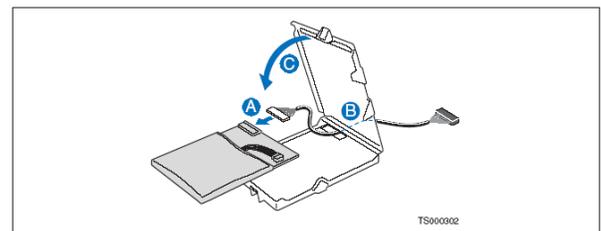| NEI	Work Instruction	Page 13 of 20
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23.	Removal of the Cable Management Bracket requires a #2 Phillips screwdriver. a. Remove the cable management bracket ("B") by loosening the blue thumbscrew ("A") that fastens it to the drive bay subassembly and pull the bracket out from the chassis ("C"). b. **Discard the bracket in the appropriate recycling bin.**	
24.	Removal of the Drive Bay Assembly requires a #2 Phillips screwdriver. a. Remove the three (3) screws that attach the drive bay front panel to the side of the chassis ("A"). b. Remove the two (2) screws on the right side of the drive bay front panel (B). c. Pull the drive bay half-way out of the chassis ("C"). d. Disconnect power cable from SFP board and IDE cable from server board. e. Pull the drive bay completely out of the chassis.	

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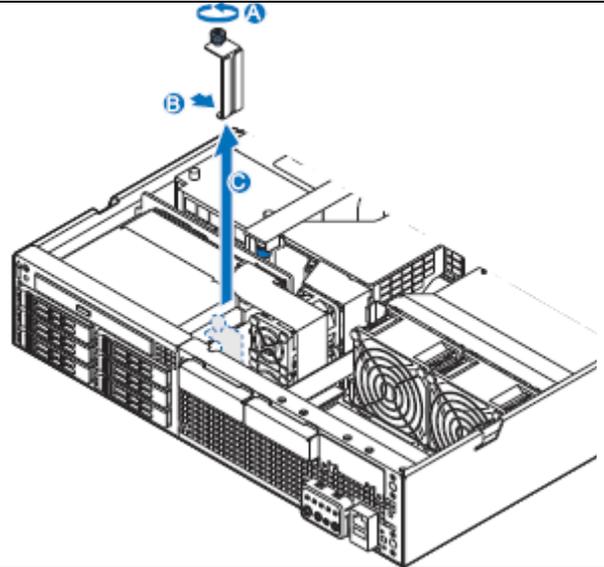| Document Number / Disk File: 597-786-0067-00	By: Tim Connolly	Current Rev: 0A	Date: 1/15/09

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24.	f. Remove the three (3) screws that attach the drive bay front panel to the side of the chassis ("A"). g. Pull the SAS backplane board off of the rear of the drive bay assembly ("B"). f. Disconnect and remove power cable from SFP board, and IDE cable from server board. f. **Discard the cables, screws, drive bay sheetmetal, and SAS back plane PCB in the appropriate recycling bin**	
25.	Removal of the Front Panel Board requires a #2 Phillips screwdriver. a. Disconnect all of cables connected to the SFP board. b. Loosening the screw that fastens the SFP board to the chassis using a #2 Philips screwdriver. ("A"). c. Carefully slide the SFP board backward toward the rear of the chassis to disengage the LED pipe assembly from behind the front control panel("B"). d. Pull the SFP board up and out of chassis ("C"). e. **Discard the cables, screws, and SFP PCB in the appropriate recycling bin**	

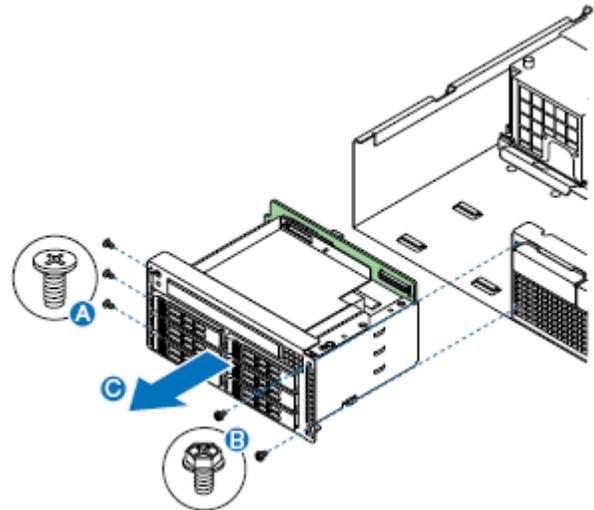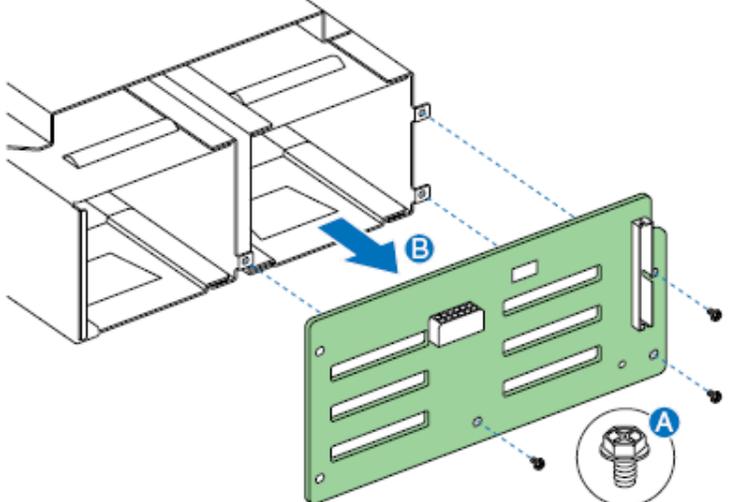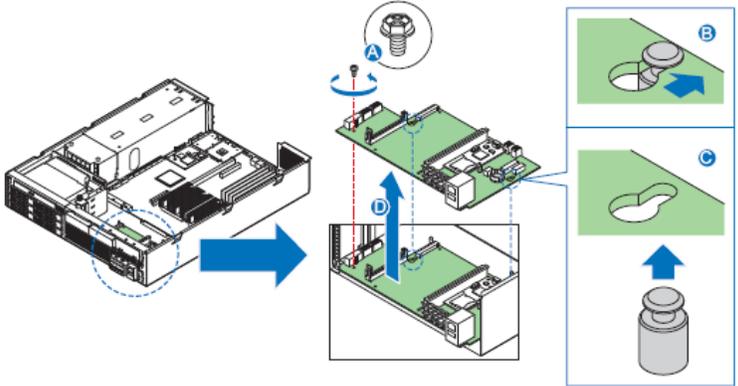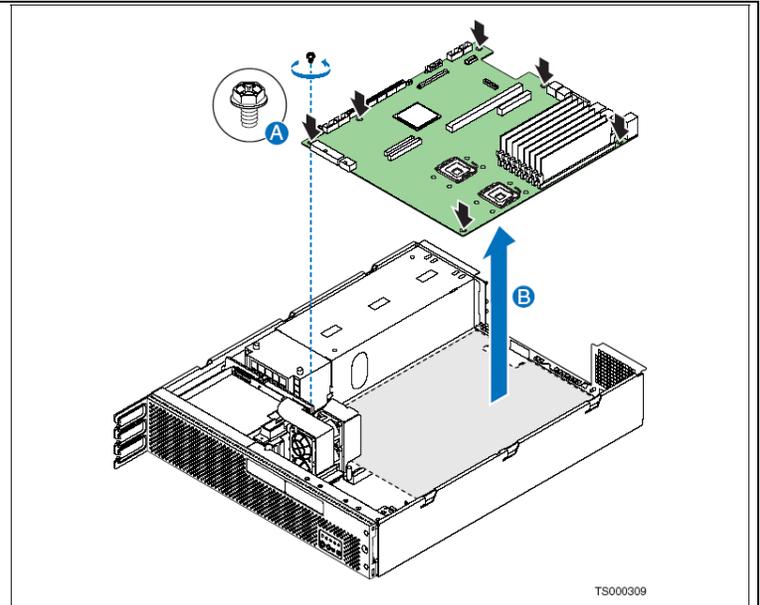| NEI	Work Instruction	Page 15 of 20
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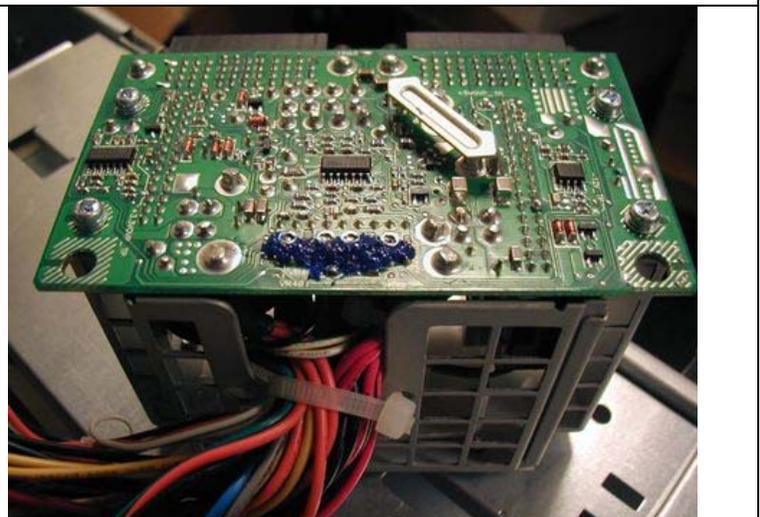| 26.	Removal of the motherboard requires a #2 Phillips screwdriver. Note: Disconnect cable hardness's from Power Distribution Board, ensure that all other cables and connectors to the motherboard have been removed. a. Remove the six (6) screws from the motherboard ("A"). b. Remove the motherboard by sliding it towards the front of the unit to disengage it from the rear panel then lift motherboard out ("B"). c. **Discard the Motherboard and screws in the appropriate recycling bin.**	
27	Removal of the Power Distribution Board requires a #2 Phillips screwdriver. a. To free the PDB assembly use your thumb press down the metal clip at the base of PDB assembly ("A"). b. Lift the PDB assembly up and out of chassis ("B").	
27	c. Remove the four (4) screws that attach the PDB to the assembly. d. **Discard the PDB, assembly housing, tie-wrap, and screws in the appropriate recycling bin.**	
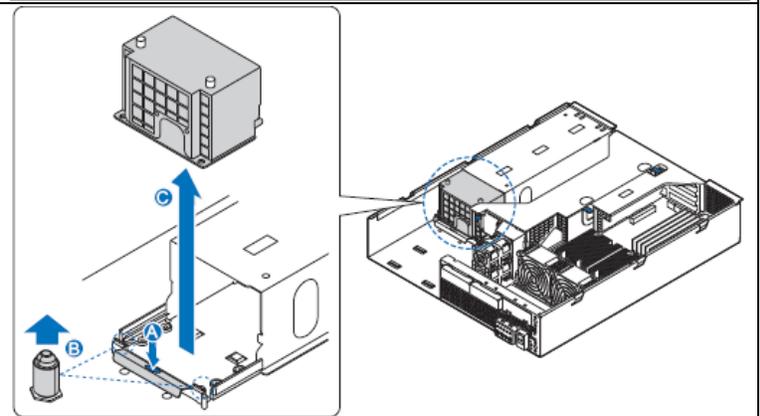
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28.	Removal of the Port Filler Panels require a #2 Phillips screwdriver.
	
	  a. One at a time , remove all three (3) filler panels from the front panel port slots by loosening two (2) screws using #2 Phillips screwdriver and pulling the filler panels down from the top edge and out.
	  b. **Discard all filer panels and screws in the appropriate recycling bin.**	
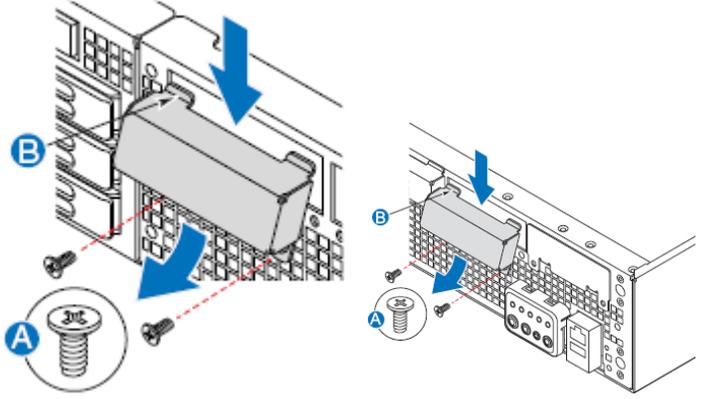
29.	Removal of the Filler Panels from the rear panel does not require any tools.
	
	  a. If present, remove all the filler panels from the rear panel by squeezing the side edges and pulling it out ("A").
	  b. **Discard all filer panels in the appropriate recycling bin.**	
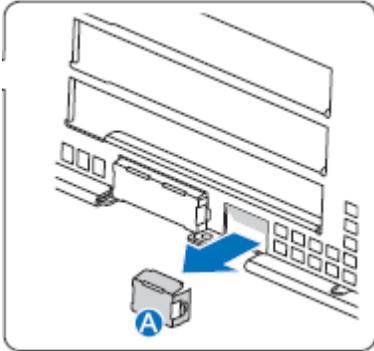
Fully Disassembled Unit

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Recycling/Material Code	Important Information
Material /Components, which must be removed and treated separately	
Lithium Battery	Battery free of hazardous substances, installed in socket on the motherboard
Printed circuit boards	Motherboard, DIMMs, Gigabit card, PCI riser boards, Power Supply, CD-ROM adapter board, & LED Board
Disk Drives	Mounted on disk carrier
Material /Components, which can disturb certain recycling processes	
Copper	Fan sink
Material /Components, through which benefits can normally be achieved	
Cold Rolled Steel	Access cover, chassis bottom, CD-ROM and Hard Drive bracket, fan tray, & Card Cage
* ABS	Shroud
Cables	Distributed in device
Fans	Fan tray
Special notes	
* Flame retardant of plastics **does not** contain PBB and PBDE.	

Title:			
Unit Disassembly for WEEE			
Document Number / Disk File: 597-786-0067-00	By: Tim Connolly	Current Rev: 0A	Date: 1/15/09
Assemblies Covered:			
C-2500 (786-0067-XX)			

Annex A

Producer:	<Company name, other on addressing the producer>
Scope of information sheet:	< Product category as in Annex IA of WEEE Directive, or type of equipment as in Annex 1B of WEEE Directive, or producer's Product Family, or single products identified by brand and model name >

Component or Material	Remarks / Location
Battery (internal *) containing Mercury (Hg)/ NiCad/Lithium/ Other	**Lithium battery** ⬇ **Located on the motherboard**
Backlighting lamps of LCD/TFT or similar screens containing Mercury (Hg)	**NONE**
Mercury (Hg) in other applications**	**NONE**
Cadmium**	**NONE**
Gas discharge lamps	**NONE**
Plastic containing ruminated flame retardants other than in Printed Circuit Assemblies ***	**NONE**
Liquid Crystal Displays with a surface greater than 100 cm2	**NONE**
Capacitors with PCB's	**NONE**
Capacitors with substances of concern**** + height > 25 mm, diameter > 25 mm or proportionately similar volume	**NONE**
Asbestos	**NONE**
Refractory ceramic fibres	**NONE**
Radio-active substances	**NONE**
Beryllium Oxide	**NONE**
Other forms of Beryllium	**BE-CU in some connector contacts** ⬇
Gasses - which fall under Regulation (EC) 2037/2000 and all hydrocarbons (HC).	**NONE**
Components with pressurised gas which need special attention (Pressure > 1,5 bar) *****	**NONE**
Liquids ***** if volume > 10 cl (or equivalence in weight, e.g. for PCB, oil...)	**NONE**
Mechanical components that store mechanical energy (i.e. springs) or equivalent parts which need special attention ***** (diameter > 10 mm and height > 25 mm or proportionally similar volume and expanding)	**NONE**
PBDE (deca- & octa-BDE) and Perfluorocatane sulfantes (PFOS) in Directive 2006/122/EC	**NONE**

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⬇ = Arrow indicates the need for the location of the compartment/ substances within the product. When the location of a substance/ components is requested, it is at part level, e.g. main board, housing etc

* Internal means that batteries can only be removed by opening the product by means of (a) tool(s).

** Substances are considered to be in the product if present above the levels specified in Commission Decision 2005/618/EC related to Directive 2002/95 (EC) (RoHS Directive) or if their use is permitted through exemptions in the Annex of Directive 2002/95(EC)

*** To be coherent with industry current standards and practices on tracking of plastic parts, Directive 2002/96 (EC) Annex II requirement is understood to focus on plastic parts that weight more than 25 g.

**** Substance of concern other than PCB, to be specified/ addressed further in the context of Directive 2002/96 (EC) Annex II national requirements and European developments

***** Needs of equivalent nature as those for maintenance, service manuals and installation for safety purposes.